



ALPHA & OMEGA
SEMICONDUCTOR

AOS Semiconductor Product Reliability Report

AO8807 rev A

Plastic Encapsulated Device

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This AOS product reliability report summarizes the qualification result for AO8807. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AO8807 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be monitored on a quarterly basis for continuously improving the product quality.

Table of Contents:

- I. Product Description
- II. Package and Die information
- III. Environmental Stress Test Summary and Result
- IV. Reliability Evaluation

I. Product Description:

The AO8807 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch.

- RoHS Compliant
- Halogen Free

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted			
Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-12	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	-6.5
		$T_A=70^\circ\text{C}$	-5
Pulsed Drain Current ^c	I_{DM}	-60	A
Power Dissipation ^b	P_D	$T_A=25^\circ\text{C}$	1.4
		$T_A=70^\circ\text{C}$	0.9
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics					
Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$t \leq 10\text{s}$	$R_{\theta JA}$	73	90	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^{AD}	Steady-State		96	125	$^\circ\text{C/W}$
Maximum Junction-to-Lead	Steady-State	$R_{\theta JL}$	63	75	$^\circ\text{C/W}$

II. Die / Package Information:

	AO8807
Process	Standard sub-micron Low voltage P channel process
Package Type	TSSOP-8
Lead Frame	Cu, D/pad, Ag spot
Die Attach	Ag epoxy
Bond wire	2 mils Au wire
Mold Material	Epoxy resin with silica filler
Flammability Rating	UL-94 V-0
Backside Metallization	Ti / Ni / Ag
Moisture Level	Up to Level 1 *

Note * based on info provided by assembler and mold compound supplier

III. Result of Reliability Stress for AO8807

Test Item	Test Condition	Time Point	Lot Attribution	Total Sample size	Number of Failures
Solder Reflow Precondition	168hr 85°C /85RH +3 cycle reflow @260°C	-	3 lots	495 pcs	0
HTGB	Temp = 150°C , Vgs=100% of Vgsmax	168hrs 500 hrs 1000 hrs	1 lot (Note A*)	77 pcs 77 pcs / lot	0
HTRB	Temp = 150°C , Vds=80% of Vdsmax	168hrs 500 hrs 1000 hrs	1 lot (Note A*)	77 pcs 77 pcs / lot	0
HAST	130 +/- 2°C , 85%RH, 33.3 psi, Vgs = 80% of Vgs max	100 hrs	3 lots (Note B**)	165 pcs 55 pcs / lot	0
Pressure Pot	121°C , 29.7psi, RH=100%	96 hrs	3 lots (Note B**)	165 pcs 55 pcs / lot	0
Temperature Cycle	-65°C to 150°C , air to air,	250 / 500 cycles	3 lots (Note B**)	165 pcs 55 pcs / lot	0

III. Result of Reliability Stress for AO8807

Continues

DPA	Internal Vision Cross-section X-ray	NA	5 5 5	5 5 5	0
CSAM		NA	5	5	0
Bond Integrity	Room Temp 150°C bake 150°C bake	0hr 250hr 500hr	40 40 40	40 wires 40 wires 40 wires	0
Solderability	245°C	5 sec	15	15 leads	0

Note A: The HTGB and HTRB reliability data presents total of available AO8807 burn-in data up to the published date.

Note B: The pressure pot, temperature cycle and HAST reliability data for AO8807 comes from the AOS generic package qualification data.

IV. Reliability Evaluation

FIT rate (per billion): 46

MTTF = 2478 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size of the selected product (AO8807). Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

$$\text{Failure Rate} = \text{Chi}^2 \times 10^9 / [2 (N) (H) (Af)] = 1.83 \times 10^9 / [2 \times 2 \times 77 \times 500 \times 258] = 46$$

$$\text{MTTF} = 10^9 / \text{FIT} = 2.17 \times 10^7 \text{ hrs} = 2478 \text{ years}$$

Chi² = Chi Squared Distribution, determined by the number of failures and confidence interval

N = Total Number of units from HTRB and HTGB tests

H = Duration of HTRB/HTGB testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [**Af**] = $\text{Exp} [E_a / k (1/T_j \text{ u} - 1/T_j \text{ s})]$

Acceleration Factor ratio list:

	55 deg C	70 deg C	85 deg C	100 deg C	115 deg C	130 deg C	150 deg C
Af	258	87	32	13	5.64	2.59	1

T_{js} = Stressed junction temperature in degree (Kelvin), K = C+273.16

T_{ju} = The use junction temperature in degree (Kelvin), K = C+273.16

k = Boltzmann's constant, 8.617164 X 10⁻⁵eV/K